

# THICKNESS ANALYSIS, USING PROFILOMETER.

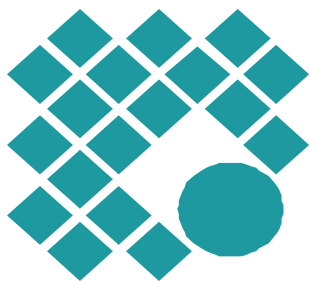


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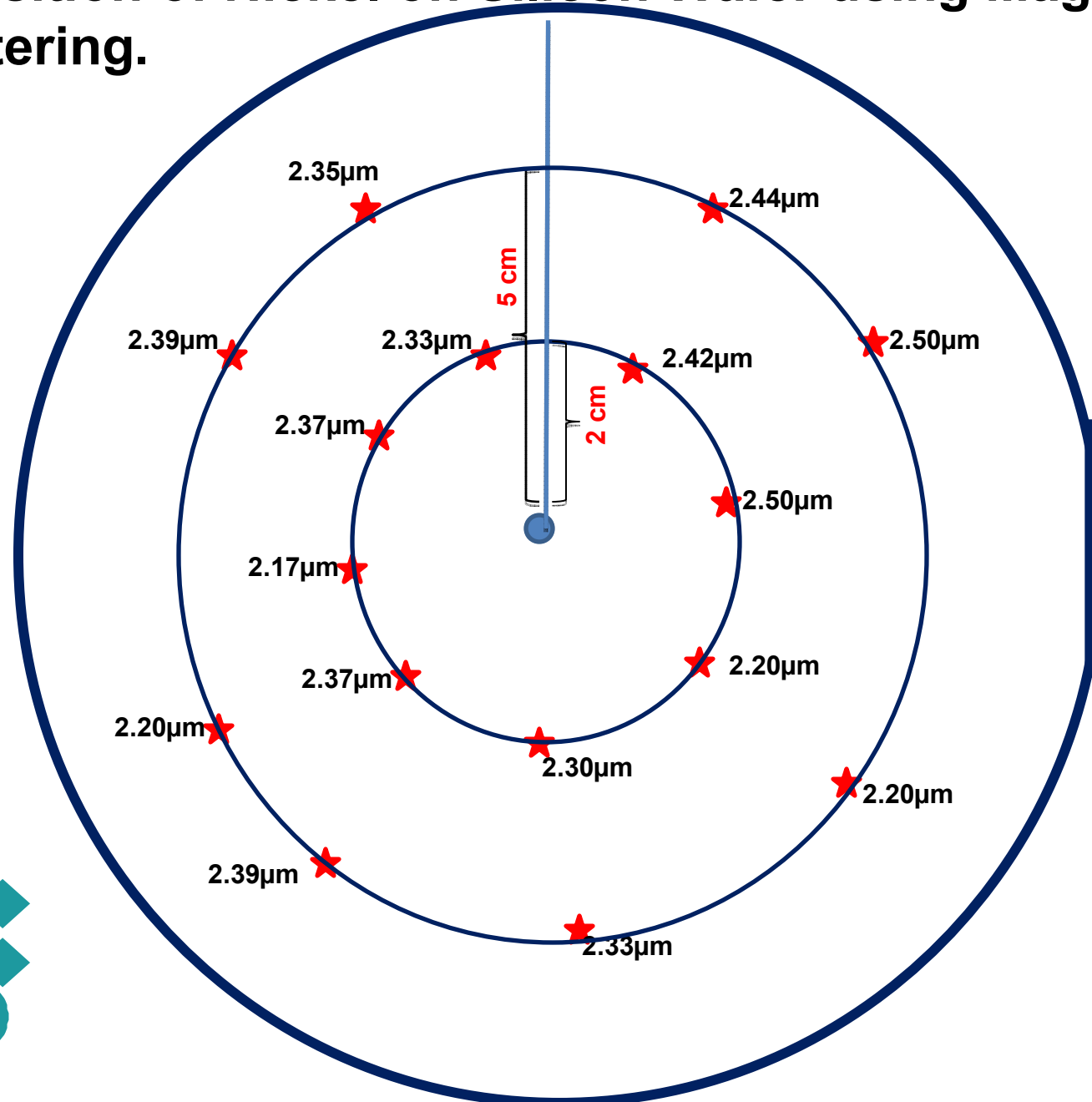
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## Parameter Used for Deposition of Nickel on Silicon wafer, Using Magnetron Sputtering.

- ❖ Substrate = Silicon Wafer.
- ❖ Target = Nickel.
- ❖ Power used = 400W.
- ❖ Sputter Pressure =  $3.38 * 10^{-3}$  torr
- ❖ Sputter time = 90 min.
- ❖ Deposition Rate =  $3.7 \text{ \AA}/\text{sec}$
- ❖ Thickness achieved =  $2 \text{ \mu m}$



- **Deposition of Nickel on Silicon Wafer using Magnetron Sputtering.**



# Result and Discussion

❖ Films are uniform, meets 7 % uniformity.

